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BSS159N E6327

EN

This Datasheet is presented by the manufacturer

DE

Dieses Datenblatt wird vom Hersteller bereitgestellt FR

Cette fiche technique est présentée par le fabricant



SIPMOS® Small-Signal-Transistor

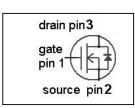
Features

- N-channel
- Depletion mode
- dv/dt rated
- \bullet Available with $V_{\rm \,GS(th)}$ indicator on reel
- Pb-free lead-plating; RoHS compliant

Product Summary

V _{DS}	60	V
R _{DS(on),max}	8	Ω
I _{DSS,min}	0.13	Α

SOT-23





Туре	Package	Pb-free	Tape and Reel Information	Marking
BSS159	PG-SOT-23	Yes	L6327: 3000 pcs/reel	SGs
BSS159	PG-SOT-23	Yes	L6906: 3000 pcs/reel sorted in V _{GS(th)} bands ¹⁾	SGs

Maximum ratings, at T_j =25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	T _A =25 °C	0.23	Α
		T _A =70 °C	0.18	
Pulsed drain current	I _{D,pulse}	T _A =25 °C	0.92	
Reverse diode dv/dt	dv/dt	$I_{\rm D}$ =0.23 A, $V_{\rm DS}$ =60 V, d <i>i</i> /d <i>t</i> =200 A/ μ s, $T_{\rm j,max}$ =150 °C	6	kV/μs
Gate source voltage	V_{GS}		±20	V
ESD sensitivity (HBM) as per MIL-STD 883			Class 0	
Power dissipation	P _{tot}	T _A =25 °C	0.36	W
Operating and storage temperature	$T_{\rm j}$, $T_{\rm stg}$		-55 150	°C
IEC climatic category; DIN IEC 68-1			55/150/56	

¹⁾ see table on next page and diagram 11



Parameter	Symbol	Symbol Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics	•					
Thermal characteristics	$R_{ m thJA}$	minimal footprint	-	-	350	K/W
Electrical characteristics, at T_j =25	5 °C, unless	otherwise specified				
Static characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =-10 V, I _D =250 μA	60	-	-	V
Gate threshold voltage	$V_{\rm GS(th)}$	V _{DS} =3 V, I _D =26 μA	-3.5	-2.8	-2.4	
Drain-source cutoff current	I _{D(off)}	V _{DS} =60 V, V _{GS} =-10 V, T _j =25 °C	-	-	0.1	μA
		V _{DS} =60 V, V _{GS} =-10 V, T _j =125 °C	-	-	10	
Gate-source leakage current	I _{GSS}	V _{GS} =20 V, V _{DS} =0 V	-	-	10	nA
On-state drain current	I _{DSS}	V _{GS} =0 V, V _{DS} =10 V	130	-	-	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =0 V, I _D =0.07 A	-	3.9	8	Ω
		V _{GS} =10 V, I _D =0.16 A	-	1.7	3.5	
Transconductance	g fs	V _{DS} >2 I _D R _{DS(on)max} , I _D =0.16 A	0.1	0.19	-	s

Threshold voltage $V_{\rm GS(th)}$ sorted in bands²⁾

J	$V_{GS(th)}$	V _{DS} =3 V, I _D =26 μA	-2.6	ı	-2.4	٧
К			-2.75	1	-2.55	
L			-2.9	-	-2.7	
M			-3.05	-	-2.85	
N			-3.2	-	-3	

²⁾ Each reel contains transistors out of one band whose identifying letter is printed on the reel label. A specific band cannot be ordered separately.



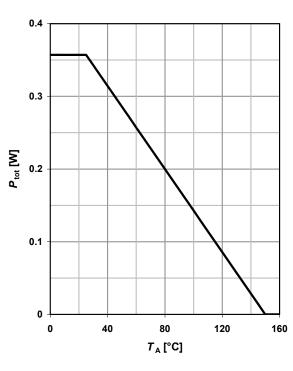
Parameter	Symbol	Symbol Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C iss		-	33	44	pF
Dynamic characteristics	C _{oss}	V _{GS} =-10 V, V _{DS} =25 V, f=1 MHz	-	8.3	11	1
Reverse transfer capacitance	C _{rss}		-	3.9	5.9	
Turn-on delay time	t _{d(on)}		-	3.1	4.7	ns
Rise time	t _r	V _{DD} =25 V, V _{GS} =-37 V,	-	2.9	4.4	
Turn-off delay time	t _{d(off)}	$I_{\rm GS}$ =-3/ V, $I_{\rm D}$ =0.16 A, $R_{\rm G}$ =6 Ω	-	9	13	
Fall time	t _f]	-	9	13	
Gate Charge Characteristics	_			1	Ī	Ī
Gate to source charge	Q _{gs}]	-	0.14	0.21	nC
Gate to drain charge	Q_{gd}	$V_{\rm DD}$ =40 V, $I_{\rm D}$ =0.16 A, $V_{\rm GS}$ =-3 to 5 V	-	0.7	1.1	
Gate charge total	Q _g		-	2.2	2.9	
Gate plateau voltage	V _{plateau}		-	-0.14	-	V
Reverse Diode						
Diode continous forward current	Is	T -25 °C	-	-	0.20	Α
Diode pulse current	I _{S,pulse}	− T _A =25 °C	-	-	0.81	
Diode forward voltage	V _{SD}	V _{GS} =-3 V, I _F =0.16 A, T _j =25 °C	-	0.79	1.2	V
Reverse recovery time	t rr	V _R =30 V, I _F =0.16 A,	-	10.4	13	ns
Reverse recovery charge	Q _{rr}	d <i>i</i> _F /d <i>t</i> =100 A/µs	_	3.3	4.1	nC

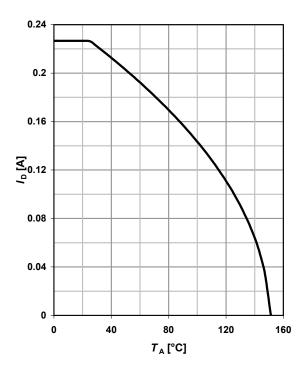


1 Power dissipation

P_{tot} =f(T_{A})

2 Drain current





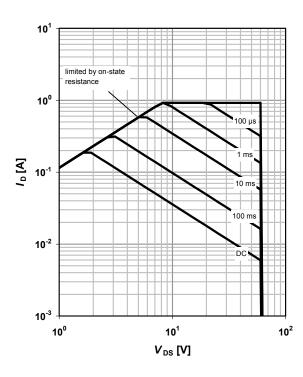
3 Safe operating area

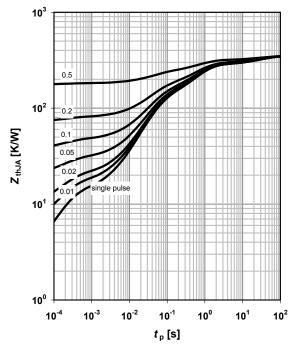
$$I_D = f(V_{DS}); T_A = 25 \text{ °C}; D = 0$$

4 Max. transient thermal impedance

$$Z_{thJA}$$
=f(t_p)

parameter: $D = t_p/T$







5 Typ. output characteristics

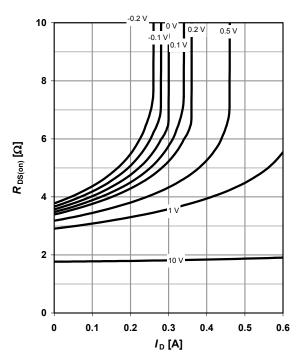
 $I_D = f(V_{DS}); T_j = 25 °C$

parameter: $V_{\rm GS}$

6 Typ. drain-source on resistance

 $R_{DS(on)}=f(I_D); T_j=25 \text{ }^{\circ}\text{C}$

parameter: $V_{\rm GS}$

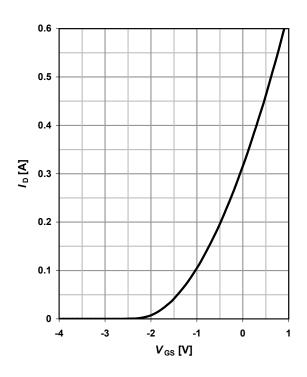


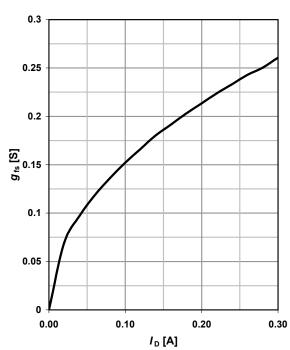
7 Typ. transfer characteristics

 I_{D} =f(V_{GS}); $|V_{DS}|$ >2 $|I_{D}|R_{DS(on)max}$

8 Typ. forward transconductance

$$g_{fs}$$
=f(I_D); T_j =25 °C

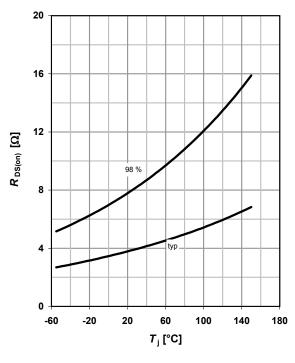






9 Drain-source on-state resistance

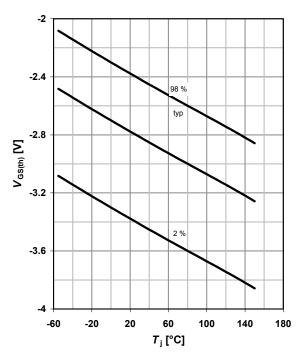
$$R_{DS(on)}$$
=f(T_j); I_D =0.07 A; V_{GS} =0 V



10 Typ. gate threshold voltage

$$V_{\text{GS(th)}}$$
=f(T_{j}); V_{DS} =3 V; I_{D} =26 μ A

parameter: I_D

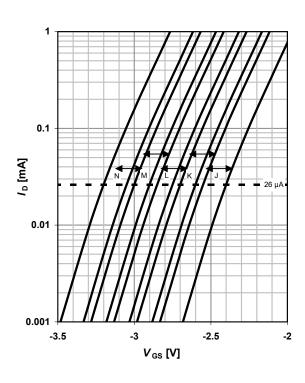


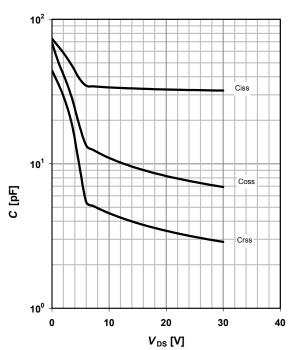
11 Threshold voltage bands

$$I_D = f(V_{GS}); V_{DS} = 3 \text{ V}; T_j = 25 ^{\circ}\text{C}$$

12 Typ. capacitances

$$C = f(V_{DS}); V_{GS} = -10 \text{ V}; f = 1 \text{ MHz}$$



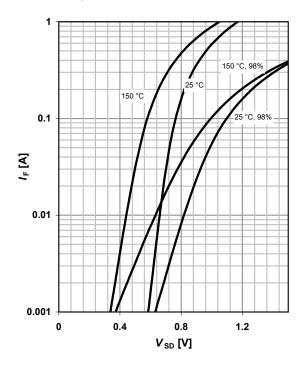




13 Forward characteristics of reverse diode

 $I_{\mathsf{F}} = \mathsf{f}(V_{\mathsf{SD}})$

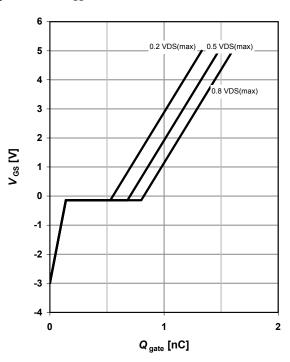
parameter: T_j



15 Typ. gate charge

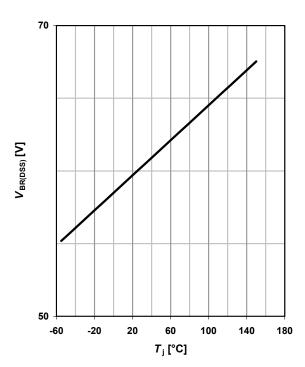
 $V_{\rm GS}$ =f($Q_{\rm gate}$); $I_{\rm D}$ =0.16 A pulsed

parameter: $V_{\rm DD}$



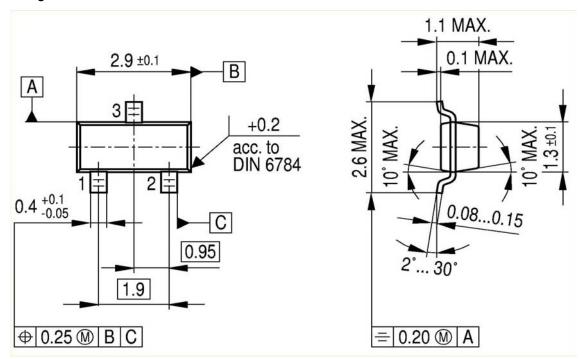
16 Drain-source breakdown voltage

 $V_{BR(DSS)}$ =f(T_j); I_D =250 μ A

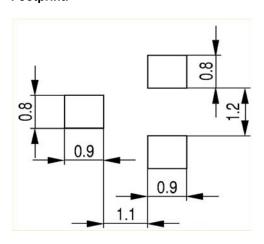




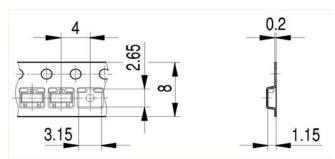
Package Outline:



Footprint:



Packaging:





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